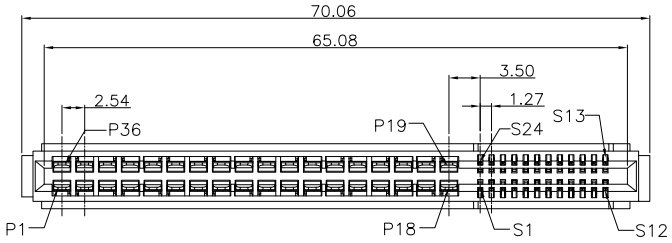
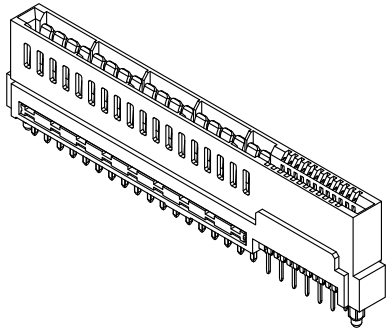
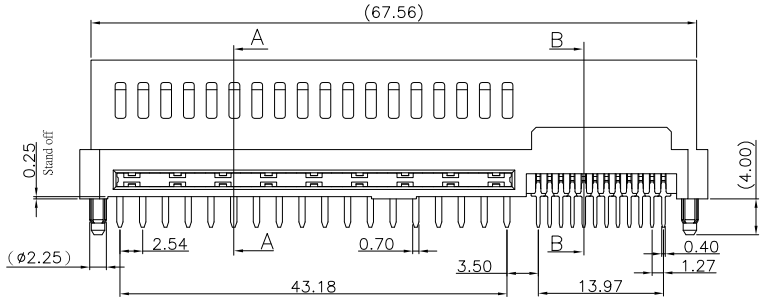
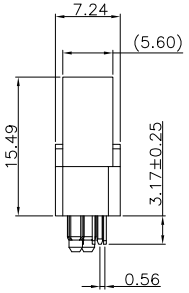
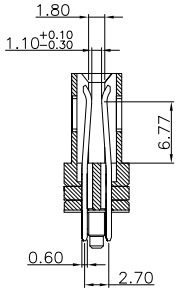
REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN230928	



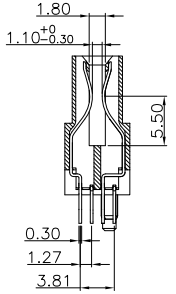




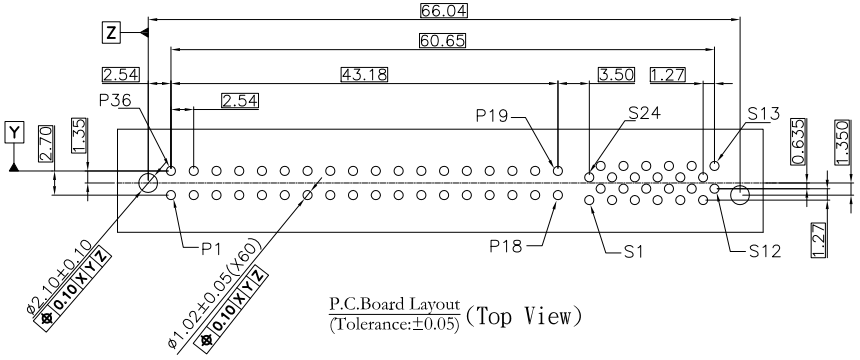




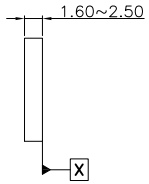
Section A-A
Scale: 1:1



Section B-B
Scale: 1:1



P.C.Board Layout
(Tolerance:±0.05) (Top View)



Material and Plating:

Housing: LCP, UL94V-0 , BLACK.
Power Contacts: High Conductivity Copper .
30u"Au+Pd/Ni on Contact Area and 80u" Min Matte Tin Plated on Solder Tail over nickel 50u" Min under plated .
Signal Contacts : Phosphor Bronze .
30u"Au+Pd/Ni on Contact Area and 80u" Min Matte Tin Plated on Solder Tail over nickel 50u" Min under plated .

Electrical Characteristics:

Current Rating: Signal Pin 1.5 AMP.
Power Pin 12.5AMP(UL).
Dielectric Withstanding Voltage:
Signal Pin DC 500V For 1 minute.
Power Pin DC 1000V For 1 minute.
Insulator Resistance: Signal Pin 500MΩ min. at DC 500V.
Power Pin 5000MΩ min. at DC 500V.
Contact Resistance: Signal Pin 25mΩ max.
Power Pin 0.6mΩ max.
Operating Temperature: -55°C ~+105°C .

***RoHS Compliant**

9302- 2 A1 S24 P 1 1 A CB30 D A

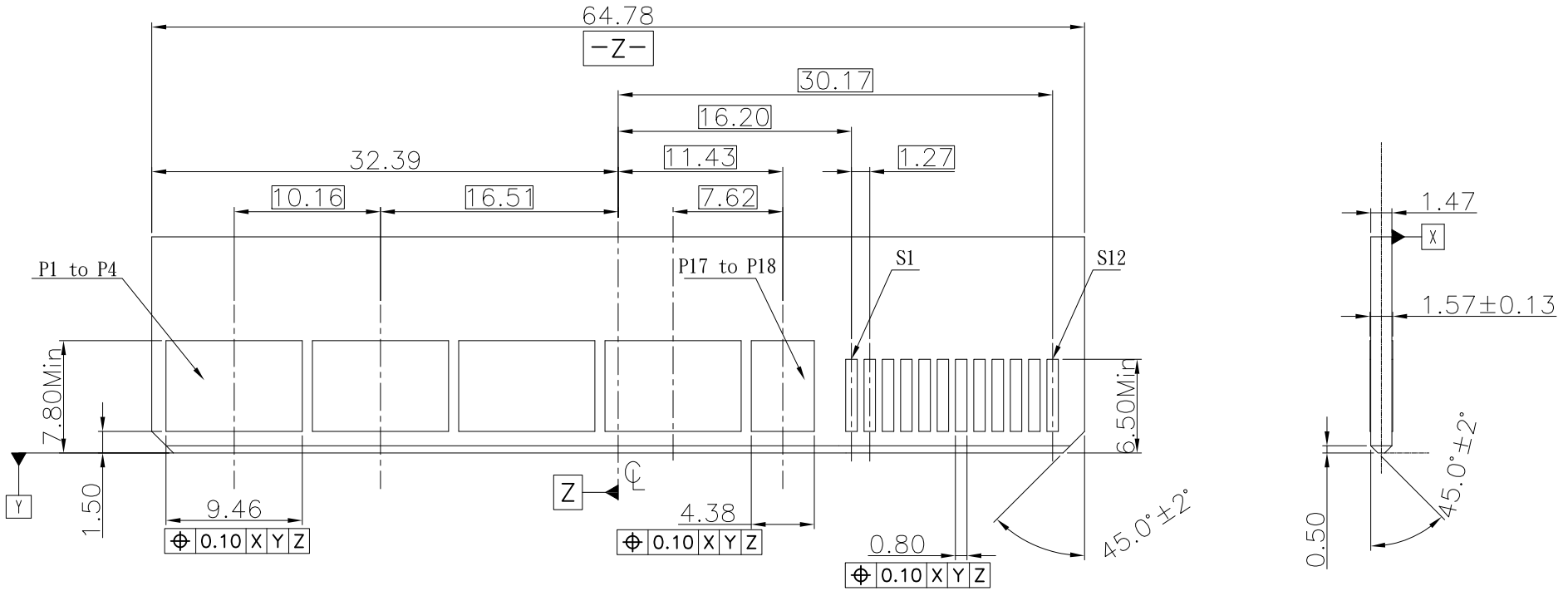
- Series — 2:Female-Straight
- A1: Power Assembly
- Sxx:Signal pin
- N:Without Post / P:With Post
- 1:DIM (Tail) 3.17mm
- 1:DIM (GAP) 1.1mm
- A:Signal pitch 1.27 / B:Signal pitch 2.54
- CB30: Contact Au+Pd/Ni , Dip Tin Power Pin:30u" / C10: (Power pin) Selective Gold Plated 10u"
- D: Dip Type
- A: Tray Package

Tolerances	Dwg. No.	9302-D0000-011	Title:
X=±0.50	Projection		9302 Series High Power and Signal Edge Card Connector
.X=±0.25	Unit mm	Scale 1:1	
.XX=±0.15	Drawn By	GYJ 09/14'23	

OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.

P/N:9302-2A1S24P11ACB30DA			
SHEET	1/2	Ver.No.	R3

REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN230928	



RECOMMENDED MATTING BOARD FOOTPRINT
(Tolerance:±0.05)

Tolerances	Dwg. No.	9302-D0000-011	Title:
X=±0.50	Projection		9302 Series High Power and Signal Edge Card Connector
.X=±0.25	Unit mm	Scale 1:1	
.XX=±0.15	Drawn By	GYJ 09/14'23	

OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.

P/N: 9302-2A1S24P11ACB30DA

SHEET 2/2 Ver.No. R3